

Title (en)
ELECTROPLATING IN PRESENCE OF CO₂

Title (de)
GALVANISIERUNG IN GEGENWART VON CO₂

Title (fr)
GALVANOPLASTIE EN PRESENCE DE CO₂

Publication
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Application
EP 05710181 A 20050214

Priority

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Abstract (en)
[origin: US2007175763A1] The present invention provides a method for conducting electroplating in the presence of CO₂ and a metal salt-containing aqueous solution, wherein the CO₂ is in the form of liquid, subcritical or supercritical, the method being characterized in that a nonionic compound having a CO₂-affinitive moiety is further added to the system where the aqueous solution and CO₂ coexist. The method of the present invention improves the efficiency of the electrochemical reaction process and enables formation of an excellent metal film.

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- No further relevant documents disclosed
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